

FIG. 1
PRIOR ART

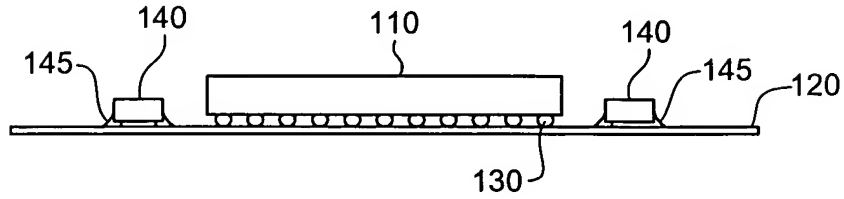


FIG. 2A

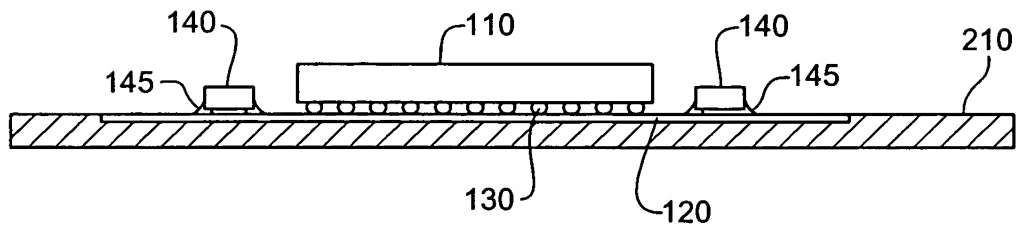


FIG. 2B

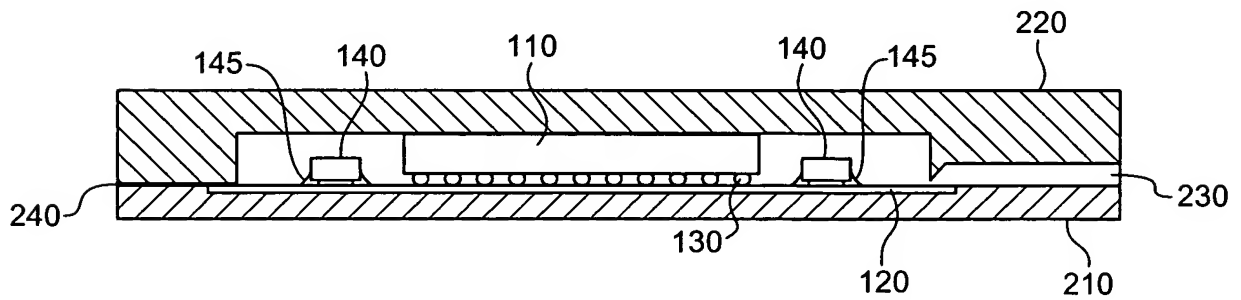


FIG. 2C



Title: "Molded Chip Package"

Inventors: Kumamoto et al. Application No.: 10/616,827 Attorney Docket No.: 42390P9482C
Blakely, Sokoloff, Taylor & Zafman 303-740-1980

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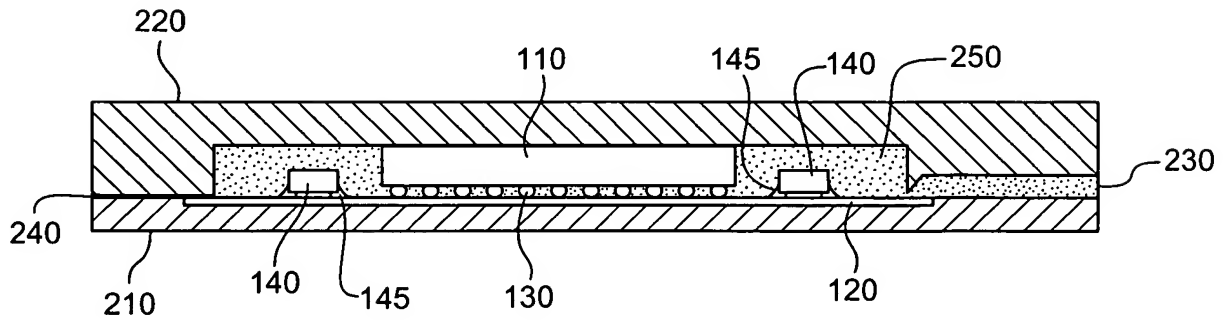


FIG. 2D

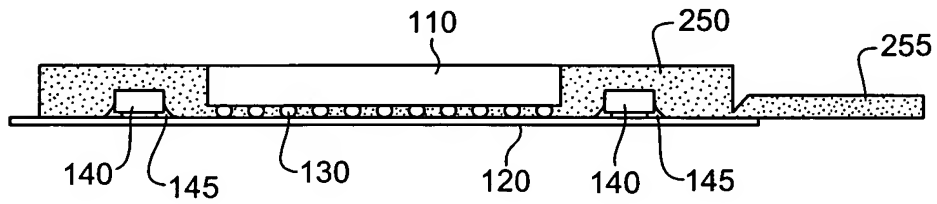


FIG. 2E

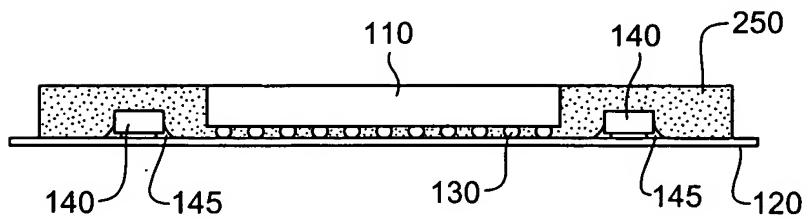


FIG. 2F



FIG. 3

